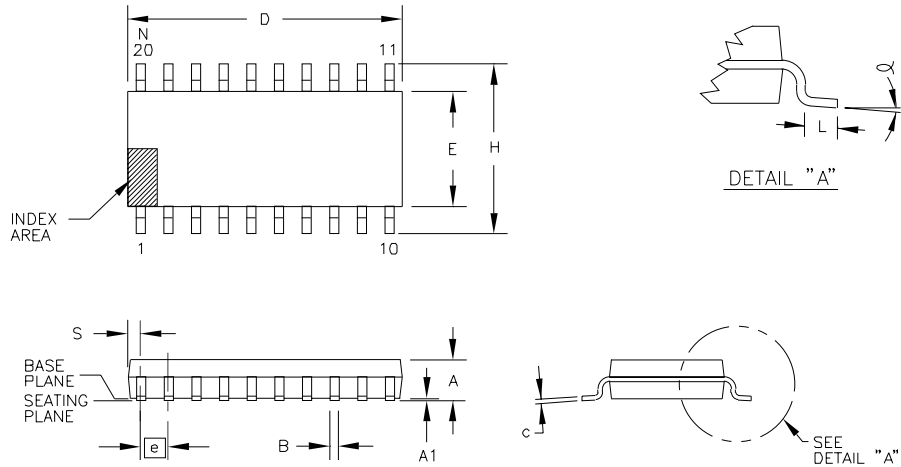


Package Number 248 - 20-Lead SOIC, .300 Wide



DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	.071	.077	1.80	1.96	
A1	.002	.006	0.05	0.15	
B	.013	.017	0.33	0.43	
c	.0076	.0082	0.19	0.21	
D	.494	.498	12.55	12.65	
E	.206	.210	5.23	5.33	
e	.050	BASIC	1.27	BASIC	
H	.303	.311	7.70	7.90	
L	.016	.031	0.40	0.80	
N	20		20		4
S	.021	.025	0.53	0.64	
α	3°	5°	3°	5°	

NOTES:

- LEADS IN TRUE POSITION WITHIN .010" (0.25 mm) @ MMC AT SEATING PLANE.
- PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.
- A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.
- N IS THE NUMBER OF TERMINAL POSITIONS.

PACKAGE NUMBER:	ZZ248	REV.:	B
JEDEC NUMBER:	NONE		